Product Information

DE-F533

Material description:	Polyimide film, white, semi-glossy, permanent adhesive, thermal transfer printable, extremely resistant top coat. Automatic dispensing has to be tested.
Application:	Ideal for barcode, datamatrix and alphanumeric identification on PCB. It can be applied to all lead and lead-free soldering processes in the market, but is not recommended for wave solder applications when applied to the bottom side of the PCB.
Material thickness:	46 µm, 75 g/m²
Adhesive:	AS1: high-temperature acrylic adhesive, solvent-based
Adhesive concentration:	25 g/m²
Adhesion:	permanent adhesion
Adhesion power:	Initial tack: 5,0N/25mm FTM9 stainless steel Shear strength 24 h: 5,0N/25mm FTM2 stainless steel
Liner:	Glassine paper
Liner thickness:	68 µm, 80 g/m²
Temperature range:	- 40 °C up to + 260 °C
Adhesion temperature:	> + 10 °C
Print methods:	Thermal transfer
Ribbon recommendation:	DE-R41, DE-R51, DE-R25
Storage:	2 years at max. 20-25 °C and 40-50% relative humidity without direct sunlight

Warranty:
Our recommendations are based on our most up-to-date knowledge and experience. As the products are used outside of our control we cannot take responsibility for any damage which may be caused when using the products. This product information sheet replaces all earlier ones. All information subject to change without notice.

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